# FEB 1 54－00 1 User＇s Guide Motor Control Evaluation Board Using the Motion－SPM ${ }^{\text {TM }}$（FSBB20CH60）in a Mini－DIP （ $44 \mathrm{~mm} \times 26.8 \mathrm{~mm}$ ）Package 

## Contents

1. Introduction........................................................................................................................................... 3
1.1 Product Description .......................................................................................................................... 3
1.2 Circuit Description........................................................................................................................... 3
2. Designed Solution.................................................................................................................................... 4
2.1 Schematic ....................................................................................................................................... 4
2.2 Bill of Materials .................................................................................................................................. 5
2.3 Printed Circuit Board ....................................................................................................................... 6

## 1. Introduction

This user's guide supports the FSBB20CH60 Motion-SPM ${ }^{\text {TM }}$ in a mini-DIP package evaluation board. It should be used in conjunction with the FSBB20CH60 data sheet and Fairchild's SPM application note AN-9035.

### 1.1 Product Description

Fairchild's Smart power Module (SPM ${ }^{\mathrm{TM}}$ ) products provide efficient motor control for energyrestricted low-power inverter-driven applications, such as washing machines and air conditioners. The FSBB20CH60 Motion-SPM ${ }^{\text {TM }}$ integrates three high-voltage ICs (HVICs), one low-voltage IC (LVIC), six IGBTs for three-phase inverter and six fast recovery diodes. Fairchild's Motion-SPM reduces board space by utilizing an ultra-compact $44 \mathrm{~mm} \times 26.8 \mathrm{~mm}$ Mini-DIP package and by incorporating built-in HVICs that provide an optocoupler-less, single supply IGBT gate driving capability. The FSBB20CH60 product offers designers high reliability with integrated under-voltage lock out (UVLO) and short circuit (SC) protection.

### 1.2 Circuit Description

The Motion-SPM is installed as the switching module in this evaluation board and has direct interface with the CPU using one shunt resistor. The $\mathrm{DC}-\operatorname{link}(\mathrm{P}$ and N$)$ input terminals are connected into the corresponding terminals in Motion-SPM and three-phase (U,V,W) output terminals from SPM are wired into motor input. Since the three HVICs are integrated in the Motion-SPM, 3 parts of bootstrap circuit are needed, which consists of bootstrap capacitor, charge resistor for charging boost capacitor, blocking diode for high voltage isolation. One shunt resistor is used for sensing short current and the related short current circuit is composed of an external shunt resistor and R-C low pass filter. The signal of fault output pin VFO drops from high level to low when a fault, such as UV (Under Voltage) or SC (Short Circuit), happens. A pull-up resistor and filter capacitor are needed to support this action. Six R-C low pass filters are used between input connector from a DSP controller (or other controllers) and gate input signal pins of Motion-SPM.

## 2. Designed Solution

### 2.1 Schematic



### 2.2 Bill of Materials

| Part No. | Rating | Characteristics | Definition |
| :---: | :---: | :---: | :---: |
| R4 | 20W, 1/4W | Carbon Film Resistor (5\%) | Bootstrap Resistor (Phase U) |
| R8 | 20W, 1/4W | Carbon Film Resistor (5\%) | Bootstrap Resistor (Phase V) |
| R9 | 20W, 1/4W | Carbon Film Resistor (5\%) | Bootstrap Resistor (Phase W) |
| R10 | 1.8kW, 1/8W | Carbon Film Resistor (5\%) | Low-Pass-Filter for Current Sensing |
| R12 | $4.7 \mathrm{~kW}, 1 / 8 \mathrm{~W}$ | Carbon Film Resistor (5\%) | Pull-Up Resistor (Fault-Out) |
| R13 | 100W, 1/8W | Carbon Film Resistor (5\%) | Series Resistor for Signal Interface (UL) |
| R14 | 100W, 1/8W | Carbon Film Resistor (5\%) | Series Resistor for Signal Interface (VL) |
| R15 | 100W, 1/8W | Carbon Film Resistor (5\%) | Series Resistor for Signal Interface (WL) |
| R16 | 100W, 1/8W | Carbon Film Resistor (5\%) | Series Resistor for Signal Interface (Fault-Out) |
| R17 | 100W, 1/8W | Carbon Film Resistor (5\%) | Series Resistor for Signal Interface (UH) |
| R18 | 100W, 1/8W | Carbon Film Resistor (5\%) | Series Resistor for Signal Interface (VH) |
| R19 | 100W, 1/8W | Carbon Film Resistor (5\%) | Series Resistor for Signal Interface (WH) |
| R21 | $15 \mathrm{~mW}, 5 \mathrm{~W}$ | Non-inductive Resistor (1\%) | Shunt Resistor for Current Sensing (OC Level: about 33A) |
| R30 | 5.6W, 1/4W | Carbon Film Resistor (5\%) | Emitter Resistor for Switching |
| R34 | 5.6W, 1/4W | Carbon Film Resistor (5\%) | Emitter Resistor for Switching |
| R35 | 5.6W, 1/4W | Carbon Film Resistor (5\%) | Emitter Resistor for Switching |
| R51 | Omit | Carbon Film Resistor (5\%) | Emitter Resistor for Switching - Refer to AN9035 |
| R52 | Omit | Carbon Film Resistor (5\%) | Emitter Resistor for Switching - Refer to AN9035 |
| R53 | Omit | Carbon Film Resistor (5\%) | Emitter Resistor for Switching - Refer to AN9035 |
| C1 | 1 nF | Ceramic Capacitor | High-Side Pull-down Capacitor (Phase U) |
| C2 | 1 nF | Ceramic Capacitor | High-Side Pull-down Capacitor (Phase V) |
| C3 | 1 nF | Ceramic Capacitor | High-Side Pull-down Capacitor (Phase W) |
| C4 | 1 nF | Ceramic Capacitor | Bypass Capacitor for Current Sensing |
| C5 | 220~F, 35V | Electrolytic Capacitor | +15V Bias Voltage Source Capacitor |
| C6 | 100 nF | Ceramic Capacitor | Bypass Capacitor for Bootstrap Supply (Phase U) |
| C7 | 6.8uF, 35V | Electrolytic Capacitor | Bootstrap Capacitor (Phase U) |
| C8 | 100nF | Ceramic Capacitor | Bypass Capacitor for Bootstrap Supply (Phase V) |
| C9 | 6.8uF, 35V | Electrolytic Capacitor | Bootstrap Capacitor (Phase V) |
| C10 | 1 nF | Ceramic Capacitor | Low-Side Pull-down Capacitor (Phase U) |
| C11 | 1 nF | Ceramic Capacitor | Low-Side Pull- down Capacitor (Phase V) |
| C 12 | 1 nF | Ceramic Capacitor | Low-Side Pull- down Capacitor (Phase W) |
| C13 | 100nF | Ceramic Capacitor | Bypass Capacitor for Bootstrap Supply (Phase W) |
| C14 | 6.8رF, 35V | Electrolytic Capacitor | Bootstrap Capacitor (Phase W) |


| Part No. | Rating | Characteristics |  |
| :--- | :--- | :--- | :--- |
| C15 | $33 n F$ | Ceramic Capacitor | Definition |
| C20 | 100nF, 630V | Film Capacitor | Capacitor for Selection of Fault Out Duration |
| C22 | 100 nF | Ceramic Capacitor | +5V Bias Voltage Bypass Capacitor |
| C23 | 1 nF | Ceramic Capacitor | By-pass Capacitor of Fault-Out Signal |
| C24 | 100нF, 16V | Electrolytic Capacitor | +5V Bias Voltage Source Capacitor |
| C26 | 1nF | Ceramic Capacitor | Bypass Capacitor for Fault-Out Signal |
| C27 | 1 FF | Ceramic Capacitor | +15V Bias Voltage Bypass Capacitor |
| C28 | 1nF | Ceramic Capacitor | Bypass Capacitor for Shunt Resistor |
| D1 | 1A, 600V | Fast Recovery Diode, (1N4937) | Bootstrap Diode (Phase U) |
| D2 | 1A, 600V | Fast Recovery Diode, (1N4937) | Bootstrap Diode (Phase V) |
| D3 | 1A, 600V | Fast Recovery Diode, (1N4937) | Bootstrap Diode (Phase W) |
| D7 | Omit | Switching Diode (Gate turn-off path) | Emitter Diode for Switching - Refer to AN9035 |
| D8 | Omit | Switching Diode (Gate turn-off path) | Emitter Diode for Switching - Refer to AN9035 |
| D15 | Omit | Switching Diode (Gate turn-off path) | Emitter Diode for Switching - Refer to AN9035 |
| U1 | FSBB20CH60 | Motion-SPM in Mini-DIP |  |

### 2.3 Printed Circuit Board

### 2.3.1 PCB Map



### 2.3.2 Circuit Layout Design

1. To avoid malfunction, the wiring of each input should be as short as possible. (less than $2-3 \mathrm{~cm}$ )
2. To prevent protection function errors, the 'R10' and 'Csc' wiring should be as short as possible.
3. All the by-pass capacitors and filter capacitors should be placed very close to SPM.
4. The short-circuit protection time constant $\mathrm{R} 10 \bullet$ CSC should be set in the range of $1 \sim 2 \mu \mathrm{sec}$.
5. The isolation distance of DC-P, U-phase, V-phase, W-phase, DC-N/GND blocks should be over 2.54 mm ( 100 mil ) for $300 \mathrm{~V}-500 \mathrm{~V}$ P-N voltage.
6. Power-GND and signal-GND should be connected with each other through only one $1.5 \sim 2 \mathrm{~mm}$ width pattern.
7. To prevent surge destruction, the wiring between the filter capacitor and the $P \&$ Ground pins should be as short as possible. The use of a high frequency non-inductive capacitor of around $0.1 \sim 0.22 \mu \mathrm{~F}$ between the $\mathrm{P} \&$ Ground pins is recommended. In addition to reducing local voltage spikes, the placement and quality of this capacitor will have a direct impact on both conducted and radiated EMI.

### 2.3.3 External Connection

| Signal Interface (J) | 1 | High-Side Input Signal from CPU (Phase U) |
| :---: | :---: | :---: |
|  | 2 | High-Side Input Signal from CPU (Phase V) |
|  | 3 | High-Side Input Signal from CPU (Phase W) |
|  | 4 | Low-Side Input Signal from CPU (Phase U) |
|  | 5 | Low-Side Input Signal from CPU (Phase V) |
|  | 6 | Low-Side Input Signal from CPU (Phase W) |
|  | 7 | Fault-Out Signal to CPU |
|  | 8 | NC |
|  | 9 | SPM Bias Supply +5V Terminal |
|  | 10 | SPM Bias Supply +15V Terminal |
|  | 11 | SPM Bias Supply Ground Terminal |
| Power Connection | P | Positive DC Link Input Connection |
|  | N | Negative DC Link Input Connection |
|  | U | Motor Input Connection (Phase U) |
|  | V | Motor Input Connection (Phase V) |
|  | W | Motor Input Connection (Phase W) |

### 2.3.4 Wiring of PCB


(a) Top Side View

(b) Bottom Side View

## WARNING AND DISCLAIMER

Replace components on the Evaluation Board only with those parts shown on the parts list in the User's Guide. Contact an authorized Fairchild representative with any questions.

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